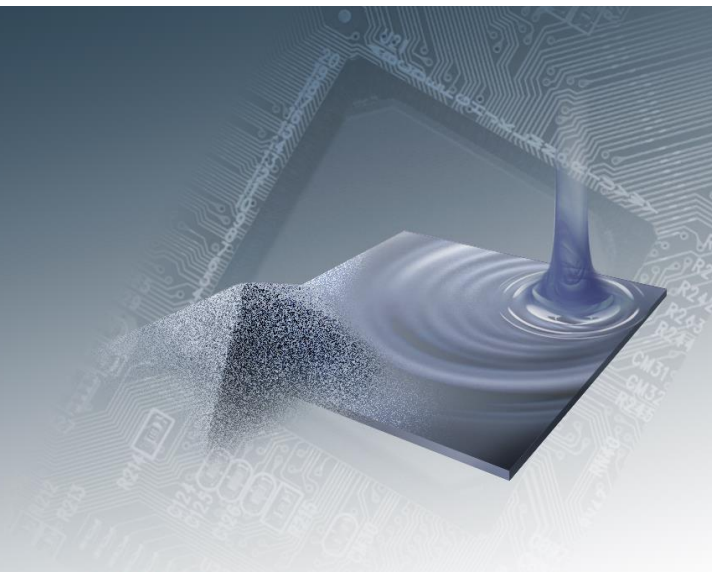


## Data Sheet

### Liquid Encapsulation Materials

### CV5350 series



Sep. 2020 No.200929-6

Partnering to go beyond.

**Electronic Materials**  
Panasonic Corporation

# Specification

Liquid encapsulant materials

## CV5350AS

### TECHNICAL INFORMATION

This is one component epoxy for Flip-chip underfilling.

### TYPICAL PROPERTIES

Properties	Unit	Data	Test Method
Viscosity(25℃)	Pa*s	4	KES 0171
Thixo,index	-	1.0	KES 0170
Gelation time(150℃)	sec	75	KES 0175

### RECOMMENDING PREHEAT CONDITION

temperature of substrate : 80~100℃

temperature of syringe : r.t.

### TYPICAL CURED PROPERTIES

**Cure Conditions : 100degC/1hour+120degC/2hour**

Properties	Unit	150℃1hour data	Test Method
Glass Trans. Temp.	℃	150	KES 0109
C.T.E.	$\times 10^{-5}/\text{℃}$	3.0	KES 0109
Flexural Strength	MPa	160	JIS K6911
Flexural Modulus	GPa	10	JIS K6911
Volume Resistivity	$\Omega \cdot \text{cm}$	$5 \times 10^{15}$	JIS K6911
Water Absorption	%	below 0.15	JIS K6911 <sup>A)</sup>
Extractable	ppm	Na <sup>+</sup> : 5	KES 0149 <sup>B)</sup>
Inpurity ion		Cl <sup>-</sup> : 18	
Conductivity	mS/m	4	KES 0147 <sup>B)</sup>

Treatment Conditions

(A):Boiled in water for 1h (B):10% boiled water for 20hrs resin was cured and crushed

\* The data in the above table are not guaranteed values.

### ATTENTION TO STORAGE

- Stored compound must be thawed before use. Warm at room temperature until no longer cool to touch (about 2hrs).
- Please use up the material within 24 hrs.
- Compound must be stored in the cool condition with sealing.(store under -20℃ in refrigerator)
- Please keep material under -20℃ after receiving product.

### ATTENTION TO HANDLING

- #Please avoid direct contact with this product by wearing gloves,protecting gears,etc.
- #Prevent frequent skin contact. If contact occurs, wash immediately with soap and water.

## ++ Before purchase ++

### 【Notes before you use】

- Please verify the suitability and fitness for intended application by quality testing, evaluation or other means at your own option before any adoption, use or change of use conditions of a product listed in the datasheet.
- We would like to have a delivery specifications mutually agreed for the product that you have decided to use. The agreements defined in the delivery specifications are assigned higher priority.
- Please note that specifications and external design are subject to change for product improvement without notice.
- For details on products in the datasheet, please contact your distributor or our sales department.

### 【Safety Information】

- Before using the product, please read the delivery specifications carefully or contact the distributor from which you purchased the product or our sales department in order to use the product correctly.
- The products in the datasheet are Semiconductor encapsulation materials for electronic and electrical devices. Please do not use them for other than specified use.

### Please Contact us of more

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